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CMB No. 0851-0011 (exp. 4/94)

05-09-2006

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To the Honorable Commissioner	1.0323	riease record the att	ached original documents or copy thereto:	
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2. Akira KOBAYASHI		Street Address:	3-1, Uchisaiwaicho 1-chome, Chiyoda-ku	
3. Kouji YAMADA		City:	Tokyo,	
4. Tsunehisa NAMIKI		State:		
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Execution Date: July 19, 2005		Additional name(s)	& address(es) attached? ☐ Yes ☒ No	
4. Application number(s) or patent numb	per(s):			
If the document is being filed together with a new application, the execution date of the application is: July 19, 2005				
A. Patent Application No(s).		B. Patent No(s).		
Additional numbers attached? Yes No				
5. Name and address of party to whom correspondence concerning document should be mailed:		6. Total number o	f applications and patents involved: one	
		7. Total fee (37 CFR 3.41) \$		
Name: HAUPTMAN KANESAKA BERNER		☐ Enclosed ☐ Authorized to	be charged to deposit account	
Patent Agents, LLP			ayment form enclosed	
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9. Signature.	_			
Manabu Kanesaka, 31,467 Manabu Kanesaka, 31,467 September 22, 2005				
Name of Person, Registration No.		Signature	Date	

PATENT

REEL: 017860 FRAME: 0014

ASSIGNMENT

For value received, we, Hideo KURASHIMA, Akira KOBAYASHI,
Kouji YAMADA and Tsunehisa NAMIKI
having post office address/residing at c/o Toyo Seikan Group
Corporate Research & Development, 22-4, Okazawacho, Hodogaya-ku,
Yokohama-shi, Kanagawa 240-0062 Japan
hereby sell, assign and transfer to <u>TOYO SEIKAN KAISHA, LTD.</u>
a corporation existing under the laws of <u>Japan</u> located at 3-1, Uchisaiwaicho 1-chome, Chiyoda-ku, Tokyo 100-8522 Japan
and its successors, assigns, and legal representatives the entire right,
title, and interest for all countries including the United States of
America, in and to certain inventions relating to
MICROWAVE PLASMA PROCESSING METHOD
described in application for Letters Patent of the United States,

described in application for Letters Patent of the United States, executed by me/us on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/We have full right so to do, and agree that I/We will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees,

Page 1 of 2

Signature	(Name)	Date 19,07,2005
Signature _.	Aliva Kofayashi	Date 19,07,2005
	(Name) Akira KOBAYASHI	
Signature ₋	Kouji YAMADA	Date 19,07, 2005
Signature _	Tsunchisa Namiki (Name)	Date / 9. 07. 2005
ignature _	Tsunehisa NAMIKI (Name)	Date
ignature _	(Name)	Date

to obtain and enforce proper protection for said invention in the United

States.

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PATENT REEL: 017860 FRAME: 0016